Irish Standard
I.S. EN 61189-5-503:2017

Test methods for electrical materials, printed board and other interconnection structures and assemblies - Part 5-503: General test method for materials and assemblies - Conductive anodic filaments (CAF) testing of circuit boards

I.S. EN 61189-5-503:2017

Incorporating amendments/corrigenda/National Annexes issued since publication:

The National Standards Authority of Ireland (NSAI) produces the following categories of formal documents:

I.S. xxx: Irish Standard — national specification based on the consensus of an expert panel and subject to public consultation.

S.R. xxx: Standard Recommendation — recommendation based on the consensus of an expert panel and subject to public consultation.

SWiFT xxx: A rapidly developed recommendatory document based on the consensus of the participants of an NSAI workshop.

This document replaces/revises/consolidates the NSAI adoption of the document(s) indicated on the CEN/CENELEC cover/Foreword and the following National document(s):

NOTE: The date of any NSAI previous adoption may not match the date of its original CEN/CENELEC document.

This document is based on:	*Published:*
EN 61189-5-503:2017	2017-08-11

This document was published under the authority of the NSAI and comes into effect on:	ICS number:
2017-08-29	31.180
	NOTE: If blank see CEN/CENELEC cover page

NSAI	T +353 1 807 3800	Sales:
1 Swift Square,	F +353 1 807 3838	T +353 1 857 6730
Northwood, Santry	E standards@nsai.ie	F +353 1 857 6729
Dublin 9	W NSAI.ie	W standards.ie

Údarás um Chaighdeáin Náisiúnta na hÉireann

National Foreword

I.S. EN 61189-5-503:2017 is the adopted Irish version of the European Document EN 61189-5-503:2017, Test methods for electrical materials, printed board and other interconnection structures and assemblies - Part 5-503: General test method for materials and assemblies - Conductive anodic filaments (CAF) testing of circuit boards

This document does not purport to include all the necessary provisions of a contract. Users are responsible for its correct application.

For relationships with other publications refer to the NSAI web store.

Compliance with this document does not of itself confer immunity from legal obligations.

In line with international standards practice the decimal point is shown as a comma (,) throughout this document.

This page is intentionally left blank

EUROPEAN STANDARD

NORME EUROPÉENNE

EUROPÄISCHE NORM

EN 61189-5-503

August 2017

ICS 31.180

English Version

Test methods for electrical materials, printed board and other interconnection structures and assemblies - Part 5-503: General test method for materials and assemblies - Conductive anodic filaments (CAF) testing of circuit boards (IEC 61189-5-503:2017)

Méthodes d'essai pour les matériaux électriques, les cartes imprimées et autres structures d'interconnexion et ensembles - Partie 5-503 : Méthodes d'essai générales pour les matériaux et les assemblages - Essais des filaments anodiques conducteurs (CAF) des cartes à circuit imprimé
(IEC 61189-5-503:2017)

Prüfverfahren für Elektromaterialien, Leiterplatten und andere Verbindungsstrukturen und Baugruppen - Teil 5-503: Allgemeine Prüfverfahren für Materialien und Baugruppen - Leitfähige anodische Fasern (CAF), Prüfung für Leiterplatten
(IEC 61189-5-503:2017)

This European Standard was approved by CENELEC on 2017-06-26. CENELEC members are bound to comply with the CEN/CENELEC Internal Regulations which stipulate the conditions for giving this European Standard the status of a national standard without any alteration.

Up-to-date lists and bibliographical references concerning such national standards may be obtained on application to the CEN-CENELEC Management Centre or to any CENELEC member.

This European Standard exists in three official versions (English, French, German). A version in any other language made by translation under the responsibility of a CENELEC member into its own language and notified to the CEN-CENELEC Management Centre has the same status as the official versions.

CENELEC members are the national electrotechnical committees of Austria, Belgium, Bulgaria, Croatia, Cyprus, the Czech Republic, Denmark, Estonia, Finland, Former Yugoslav Republic of Macedonia, France, Germany, Greece, Hungary, Iceland, Ireland, Italy, Latvia, Lithuania, Luxembourg, Malta, the Netherlands, Norway, Poland, Portugal, Romania, Serbia, Slovakia, Slovenia, Spain, Sweden, Switzerland, Turkey and the United Kingdom.

European Committee for Electrotechnical Standardization
Comité Européen de Normalisation Electrotechnique
Europäisches Komitee für Elektrotechnische Normung

CEN-CENELEC Management Centre: Avenue Marnix 17, B-1000 Brussels

EN 61189-5-503:2017

European foreword

The text of document 91/1433/FDIS, future edition 1 of IEC 61189-5-503, prepared by IEC/TC 91 "Electronics assembly technology" was submitted to the IEC-CENELEC parallel vote and approved by CENELEC as EN 61189-5-503:2017.

The following dates are fixed:

• latest date by which the document has to be implemented at national level by publication of an identical national standard or by endorsement	(dop)	2018-03-26
• latest date by which the national standards conflicting with the document have to be withdrawn	(dow)	2020-06-26

Attention is drawn to the possibility that some of the elements of this document may be the subject of patent rights. CENELEC shall not be held responsible for identifying any or all such patent rights.

Endorsement notice

The text of the International Standard IEC 61189-5-503:2017 was approved by CENELEC as a European Standard without any modification.

In the official version, for Bibliography, the following notes have to be added for the standards indicated:

IEC 60068-3-4	NOTE	Harmonized as EN 60068-3-4.
IEC 60068-3-5	NOTE	Harmonized as EN 60068-3-5.
IEC 60721-1	NOTE	Harmonized as EN 60721-1.
IEC 60721-2-1	NOTE	Harmonized as EN 60721-2-1.
IEC 60721-3-0	NOTE	Harmonized as EN 60721-3-0.

Annex ZA
(normative)
Normative references to international publications with their corresponding European publications

The following documents, in whole or in part, are normatively referenced in this document and are indispensable for its application. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

NOTE 1 When an International Publication has been modified by common modifications, indicated by (mod), the relevant EN/HD applies.

NOTE 2 Up-to-date information on the latest versions of the European Standards listed in this annex is available here: www.cenelec.eu.

Publication	Year	Title	EN/HD	Year
IEC 60068-1	2013	Environmental testing -- Part 1: General and guidance	EN 60068-1	2014
IEC 60068-2-30	-	Environmental testing -- Part 2-30: Tests - Test Db: Damp heat, cyclic (12 h + 12 h cycle)	EN 60068-2-30	-
IEC 60068-2-38	-	Environmental testing -- Part 2-38: Tests - Test Z/AD: Composite temperature/humidity cyclic test	EN 60068-2-38	-
IEC 60068-2-66	-	Environmental testing -- Part 2-66: Test methods - Test Cx: Damp heat, steady state (unsaturated pressurized vapour)	EN 60068-2-66	-
IEC 60068-2-67	-	Environmental testing -- Part 2: Tests - Test Cy: Damp heat, steady state, accelerated test primarily intended for components	EN 60068-2-67	-
IEC 60068-2-78	-	Environmental testing -- Part 2-78: Tests - Test Cab: Damp heat, steady state	EN 60068-2-78	-
IEC 60194	-	Printed board design, manufacture and assembly - Terms and definitions	-	-
IPC-TM-650 No 2.6.14.1	-	Electrochemical Migration Resistance Test	-	-
IPC-TM-650 No 2.6.25	-	Conductive Anodic Filament (CAF) Resistance Test: X-Y Axis	-	-

This page is intentionally left blank

IEC 61189-5-503

Edition 1.0 2017-05

INTERNATIONAL STANDARD

colour inside

Test methods for electrical materials, printed board and other interconnection structures and assemblies – Part 5-503: General test method for materials and assemblies – Conductive anodic filaments (CAF) testing of circuit boards

IEC 61189-5-503:2017-05(en)

IEC Central Office
3, rue de Varembé
CH-1211 Geneva 20
Switzerland

Tel.: +41 22 919 02 11
Fax: +41 22 919 03 00
info@iec.ch
www.iec.ch

IEC 61189-5-503

Edition 1.0 2017-05

INTERNATIONAL STANDARD

Test methods for electrical materials, printed board and other interconnection structures and assemblies – Part 5-503: General test method for materials and assemblies – Conductive anodic filaments (CAF) testing of circuit boards

INTERNATIONAL
ELECTROTECHNICAL
COMMISSION

ICS 31.180

ISBN 978-2-8322-4320-6

CONTENTS

INTERNATIONAL ELECTROTECHNICAL COMMISSION

_____

TEST METHODS FOR ELECTRICAL MATERIALS, PRINTED BOARD AND OTHER INTERCONNECTION STRUCTURES AND ASSEMBLIES –

Part 5-503: General test method for materials and assemblies – Conductive anodic filaments (CAF) testing of circuit boards

FOREWORD

1) The International Electrotechnical Commission (IEC) is a worldwide organization for standardization comprising all national electrotechnical committees (IEC National Committees). The object of IEC is to promote international co-operation on all questions concerning standardization in the electrical and electronic fields. To this end and in addition to other activities, IEC publishes International Standards, Technical Specifications, Technical Reports, Publicly Available Specifications (PAS) and Guides (hereafter referred to as "IEC Publication(s)"). Their preparation is entrusted to technical committees; any IEC National Committee interested in the subject dealt with may participate in this preparatory work. International, governmental and non-governmental organizations liaising with the IEC also participate in this preparation. IEC collaborates closely with the International Organization for Standardization (ISO) in accordance with conditions determined by agreement between the two organizations.
2) The formal decisions or agreements of IEC on technical matters express, as nearly as possible, an international consensus of opinion on the relevant subjects since each technical committee has representation from all interested IEC National Committees.
3) IEC Publications have the form of recommendations for international use and are accepted by IEC National Committees in that sense. While all reasonable efforts are made to ensure that the technical content of IEC Publications is accurate, IEC cannot be held responsible for the way in which they are used or for any misinterpretation by any end user.
4) In order to promote international uniformity, IEC National Committees undertake to apply IEC Publications transparently to the maximum extent possible in their national and regional publications. Any divergence between any IEC Publication and the corresponding national or regional publication shall be clearly indicated in the latter.
5) IEC itself does not provide any attestation of conformity. Independent certification bodies provide conformity assessment services and, in some areas, access to IEC marks of conformity. IEC is not responsible for any services carried out by independent certification bodies.
6) All users should ensure that they have the latest edition of this publication.
7) No liability shall attach to IEC or its directors, employees, servants or agents including individual experts and members of its technical committees and IEC National Committees for any personal injury, property damage or other damage of any nature whatsoever, whether direct or indirect, or for costs (including legal fees) and expenses arising out of the publication, use of, or reliance upon, this IEC Publication or any other IEC Publications.
8) Attention is drawn to the Normative references cited in this publication. Use of the referenced publications is indispensable for the correct application of this publication.
9) Attention is drawn to the possibility that some of the elements of this IEC Publication may be the subject of patent rights. IEC shall not be held responsible for identifying any or all such patent rights.

International Standard IEC 61189-5-503 been prepared by IEC technical committee 91: Electronics assembly technology.

The text of this standard is based on the following documents:

FDIS	Report on voting
91/1433/FDIS	91/1443/RVD

Full information on the voting for the approval of this International Standard can be found in the report on voting indicated in the above table.

This document has been drafted in accordance with the ISO/IEC Directives, Part 2.

A list of all parts in the IEC 61189 series, published under the general title *Test methods for electrical materials, printed boards and other interconnection structures and assemblies*, can be found on the IEC website.

The committee has decided that the contents of this document will remain unchanged until the stability date indicated on the IEC website under "http://webstore.iec.ch" in the data related to the specific document. At this date, the document will be

- reconfirmed,
- withdrawn,
- replaced by a revised edition, or
- amended.

A bilingual version of this publication may be issued at a later date.

IMPORTANT – The 'colour inside' logo on the cover page of this publication indicates that it contains colours which are considered to be useful for the correct understanding of its contents. Users should therefore print this document using a colour printer.

TEST METHODS FOR ELECTRICAL MATERIALS, PRINTED BOARD AND OTHER INTERCONNECTION STRUCTURES AND ASSEMBLIES –

Part 5-503: General test method for materials and assemblies – Conductive anodic filaments (CAF) testing of circuit boards

1 Scope

This part of IEC 61189 specifies the conductive anodic filament (hereafter referred to as CAF) and specifies not only the steady-state temperature and humidity test, but also a temperature-humidity cyclic test and an unsaturated pressurized vapour test (HAST).

2 Normative references

The following documents are referred to in the text in such a way that some or all of their content constitutes requirements of this document. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

IEC 60068-1:2013, *Environmental testing – Part 1: General and guidance*

IEC 60068-2-30, *Environmental testing – Part 2-30: Tests – Test Db: Damp heat, cyclic (12 h + 12 h cycle)*

IEC 60068-2-38, *Environmental testing – Part 2-38: Tests – Test Z/AD: Composite temperature/humidity cyclic test*

IEC 60068-2-66, *Environmental testing – Part 2: Test methods – Test Cx: Damp heat, steady state (unsaturated pressurized vapour)*

IEC 60068-2-67, *Environmental testing – Part 2: Tests – Test Cy: Damp heat, steady state, accelerated test primarily intended for components*

IEC 60068-2-78, *Environmental testing – Part 2-78: Tests – Test Cab: Damp heat, steady state*

IEC 60194, *Printed board design, manufacture and assembly – Terms and definitions*

IPC-TM-650 No.2.6.14.1, *Electrochemical Migration Resistance Test [viewed 2017-01-31]. Available at: https://www.ipc.org/TM/2-6_2-6-14-1.pdf*

IPC-TM-650 No.2.6.25, *Conductive Anodic Filament (CAF) Resistance Test: X-Y Axis [viewed 2017-01-31]. Available at: https://www.ipc.org/4.0_Knowledge/4.1_Standards/test/2-6-25.pdf*

3 Terms and definitions

For the purposes of this document, the terms and definitions given in IEC 60194 and IEC 60068-1 as well as the following apply.

ISO and IEC maintain terminological databases for use in standardization at the following addresses: